

**ELECTRICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	TYP.	MAX.	UNITS
Forward voltage drop See fig. 1	$V_{FM}^{(1)}$	19 A	-	0.41	V
		40 A		0.52	
		19 A	0.25	0.33	
		40 A		0.50	
Reverse leakage current See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	10	mA
		$T_J = 100\text{ }^{\circ}\text{C}$	-	600	
Threshold voltage	$V_{F(TO)}$	$T_J = T_J \text{ maximum}$	0.182		V
Forward slope resistance	r_t		7.6		m Ω
Maximum junction capacitance	C_T	$V_R = 5\text{ V}_{DC}$, (test signal range 100 kHz to 1 MHz), $25\text{ }^{\circ}\text{C}$	-	2000	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body	8	-	nH
Maximum voltage rate of change	dV/dt	Rated V_R	10 000		V/ μs

Note(1) Pulse width < 300 μs , duty cycle < 2 %**THERMAL - MECHANICAL SPECIFICATIONS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction temperature range	T _J		-55 to +125	°C
Maximum storage temperature range	T _{Stg}		-55 to +150	
Maximum thermal resistance, junction to case	R _{thJC}	DC operation See fig. 4	1.5	°C/W
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased (For TO-220)	0.50	
Maximum thermal resistance, junction to ambient	R _{thJA}	DC operation	40	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum	Non-lubricated threads	6 (5)	kgf · cm (lbf · in)
	maximum		12 (10)	
Marking device		Case style D ² PAK	20L15TS	

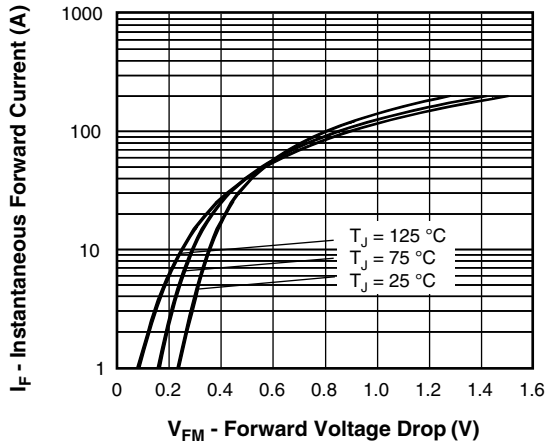


Fig. 1 - Maximum Forward Voltage Drop Characteristics

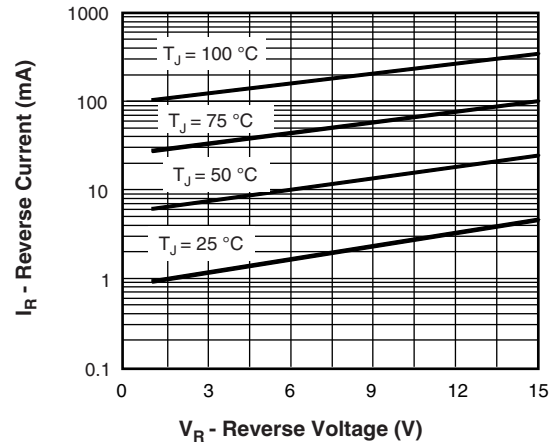


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

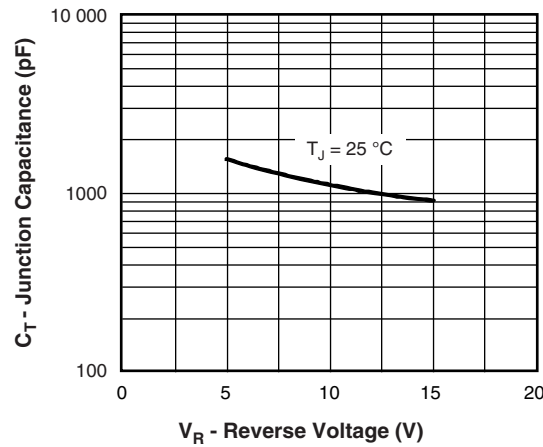


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

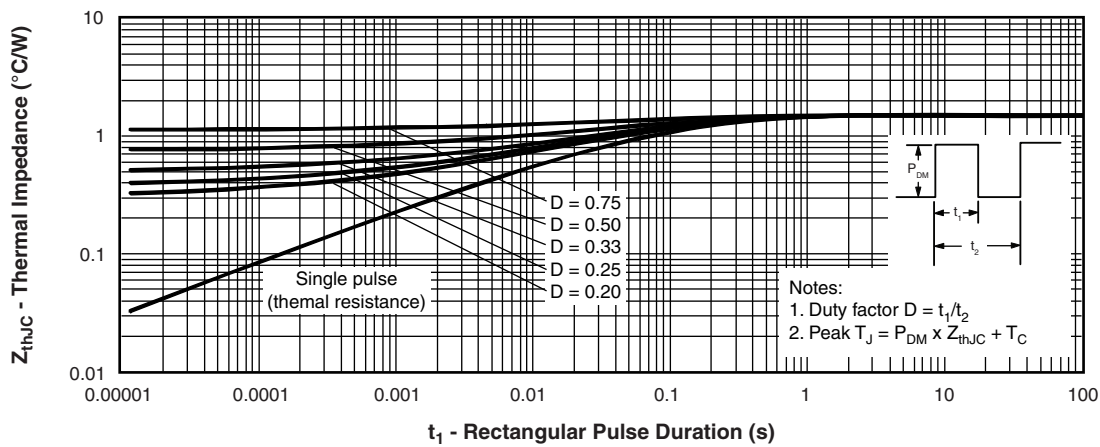


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

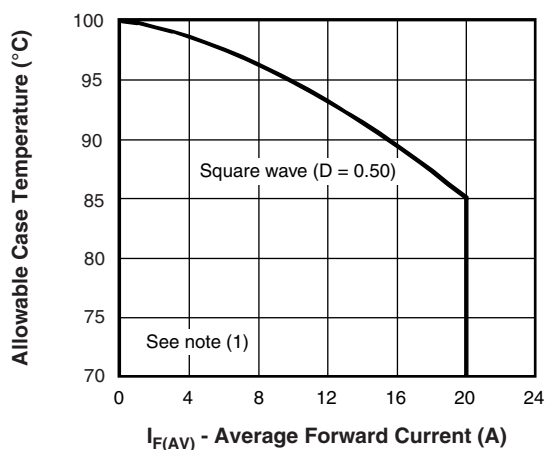


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

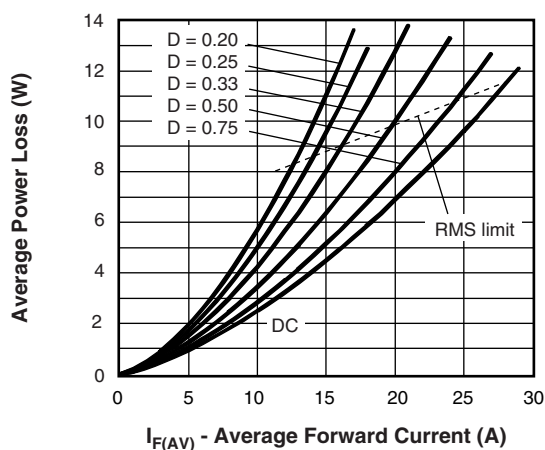


Fig. 6 - Forward Power Loss Characteristics

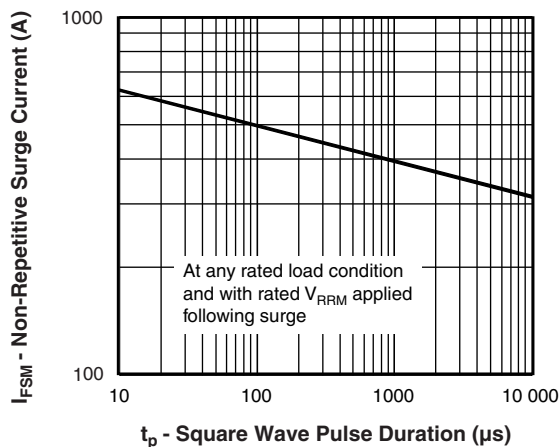


Fig. 7 - Maximum Non-Repetitive Surge Current

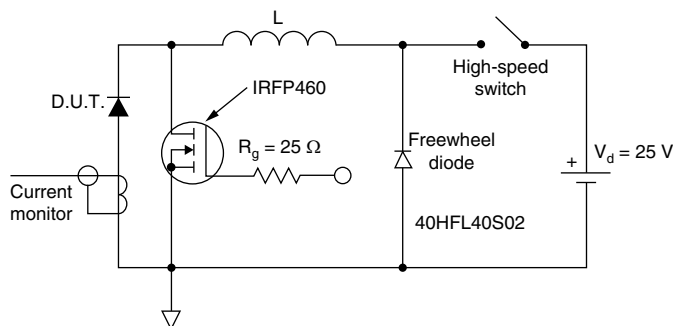


Fig. 8 - Unclamped Inductive Test Circuit

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 P_{dREV} = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\%$ rated V_R

**ORDERING INFORMATION TABLE**

Device code	VS-	20	L	15	T	S	TRL	PbF
	1	2	3	4	5	6	7	8
1	- Vishay Semiconductors product							
2	- Current rating (20 A)							
3	- L = Low V_F							
4	- Voltage rating (15 = 15 V)							
5	- T = Schottky series							
6	- S = D ² PAK							
7	- • None = tube • TRL = tape and reel (left oriented) • TRR = tape and reel (right oriented)							
8	- PbF = lead (Pb)-free							

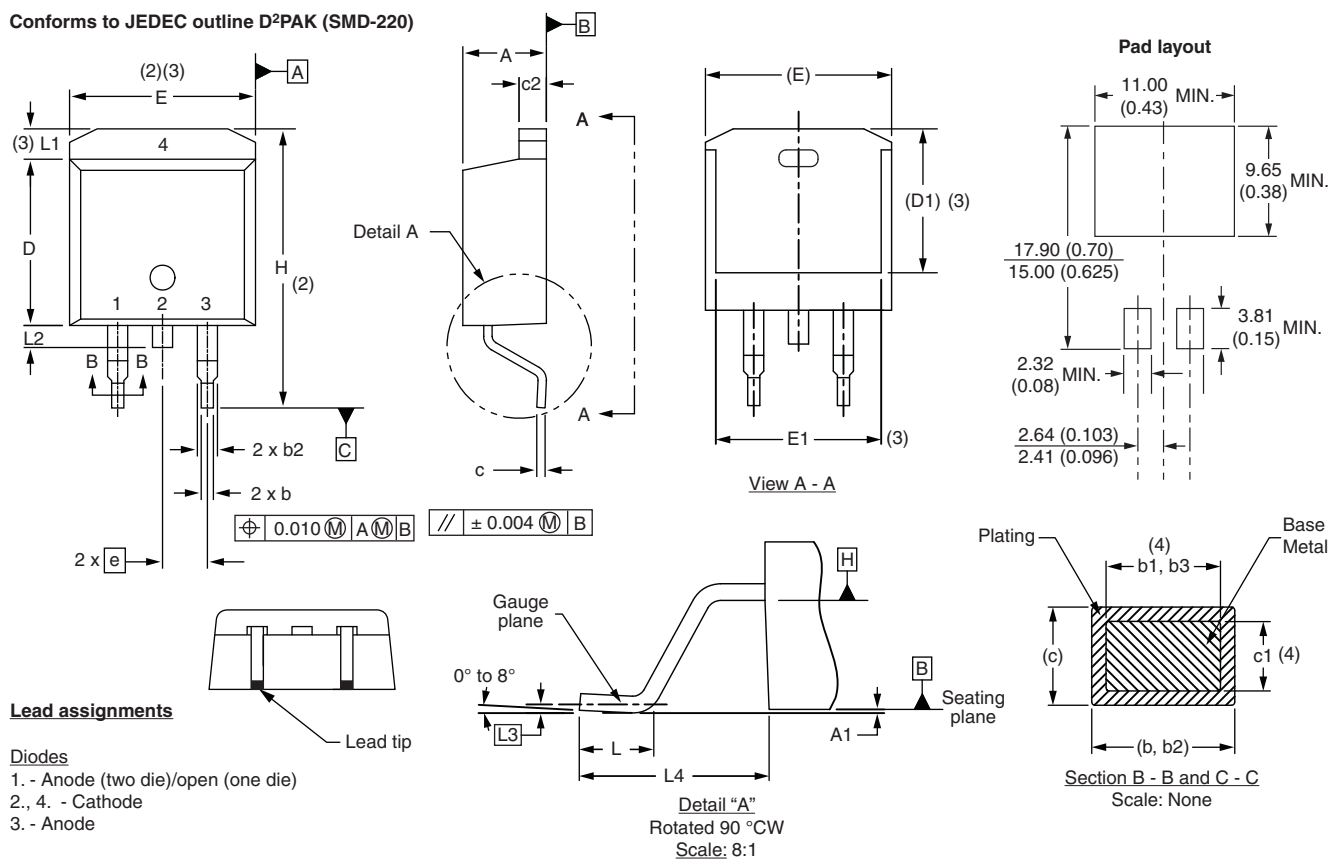
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-20L15TSPbF	50	1000	Antistatic plastic tubes
VS-20L15TSTRLPbF	800	800	13" diameter reel
VS-20L15TSTRRPbF	800	800	13" diameter reel
VS-20L15T-1PbF	50	1000	Antistatic plastic tubes

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95014
Part marking information	www.vishay.com/doc?95008
Packaging information	www.vishay.com/doc?95032

D²PAK, TO-262

DIMENSIONS - D²PAK in millimeters and inches

Conforms to JEDEC outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

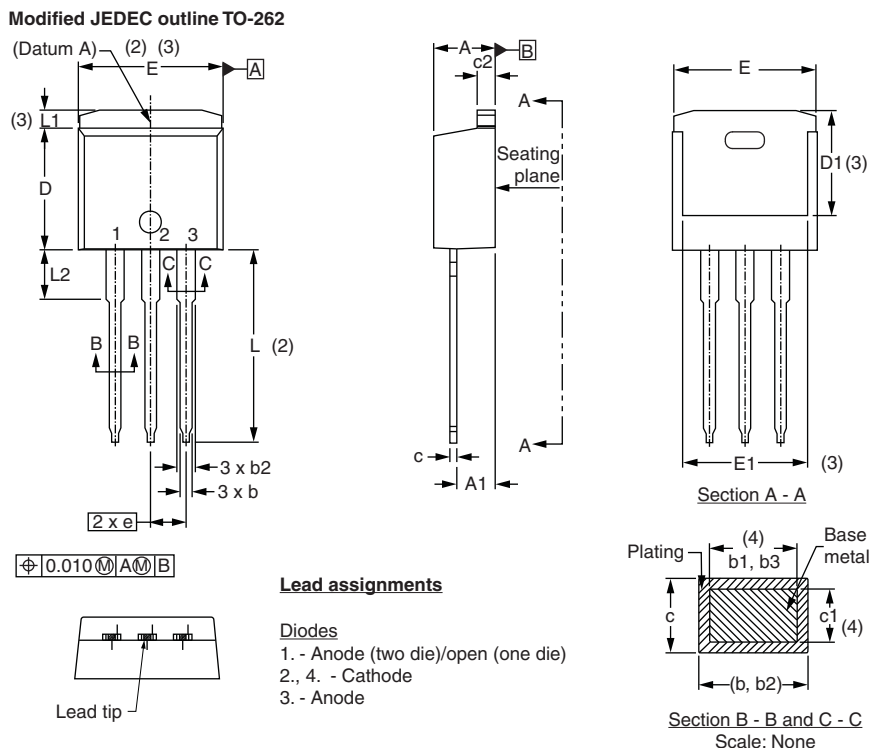
SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

- (7) Outline conforms to JEDEC outline TO-263AB

DIMENSIONS - TO-262 in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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